

Product Bulletin Document #: PB21295Z

Issue Date: 12 April 2016

Title of Change:	NCV7462 Datasheet Update – Revision 4				
Effective date:	12 April 2016				
Contact information:	Contact your local ON Semiconductor Sales Office or Roman Buzas <roman.buzas@onsemi.com></roman.buzas@onsemi.com>				
Type of notification:	ation: ON Semiconductor will consider this change accepted.				
Change category: ☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other					
Change Sub-Category(s): Manufacturing Site Change Manufacturing Process Change				☑ Datasheet/Product Doc change☑ Shipping/Packaging/Marking☑ Other:	
Sites Affected: ☐ All site(s) ☐ ON Semiconductor site(s)		☐ External Foundry/Subcon site(s)			
Description and Purpose:					
Moisture Sensitivity Level (MSL) changed • MSL changed from 2 to 3 (page 6) • See FPCN20927ZC for more details					
Electrical Characteristics • Digital pin input hysteresis (Vin_hys_pinx) limit changed (page 26)					
New Product Version ID added (due to new manufacture location) Device ROM SPI register PRODUCT VERSION (page 42) \$4404 = Fab2 \$5104 = Gresham					
Package drawing updated to the latest revision Modified dimension A2 min value Modified dimension b max value					
Minor text corrections • Pin numbers of CANH and VSPLIT were swapped in the Block diagram (page 2, Figure 1) and Typical application diagram (page 5, Figure 3)					
Electrical Characteristic Summary:					
Digital pin input hysteresis (Vin_hys_pinx) limit changed (page 26)					
Original Datasheet					
 	voltage vresis	100	500	m∨	
Updated Datasheet					
 	voltage resis	60	500	mV	
List of affected Standard Parts: NCV7462DQ0R2G					

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